Amphenol

COMMUNICATIONS SOLUTIONS

www.amphenol-cs.com

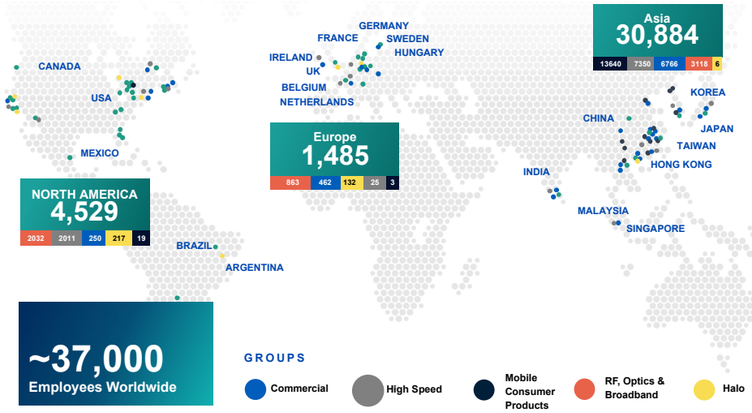
Amphenol

Amphenol Communications Solutions (ACS), a division of Amphenol Corporation, is a world leader in interconnect solutions for Communications, Mobile, RF, Optics, and Commercial electronics markets.

Amphenol Corporation is one of the world's largest designers and manufacturers of electrical, electronic and fiber optic connectors and interconnect systems, antennas, sensors and sensor-based products and coaxial and high-speed specialty cable.

ACS has an expansive global presence in research and development, manufacturing, and sales. We design and manufacture a wide range of innovative connectors as well as cable assemblies for diverse applications including server, storage, data center, mobile, RF, networking, industrial, business equipment and automotive.

Strong Global Presence



Application and Market Solutions

Custom Capabilities

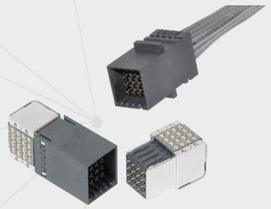
Our engineering teams collaborate with our customers on thousands of projects every year, so no matter what technical, operational and even commercial challenges you face, Amphenol Communciations Solutions can develop a solution for you!

www.amphenol-cs.com

Product Overview

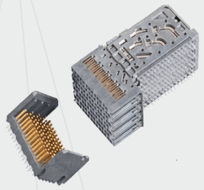
High Speed Backplane Products

www.amphenol-cs.com/high-speed-backplane



Paladin HD2

- Industry leading SI performance supporting 224Gb/s data rates
- Optimized to maximize density with 144 diff pairs within 1U orthogonal slot
- Consistent signal integrity performance over the entire mating range
- Flexible architecture supports right angle female, direct orthogonal, and cables up to 12P

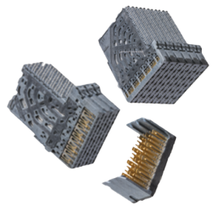


XCede® HD

- Supports designs from 8G to 56G PAM4
- The de facto standard for high performance backplane designs with industry leading density
- Supports Embedded Capacitors

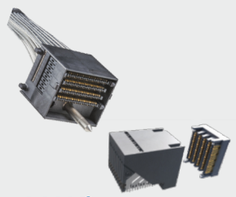
Paladin®

- Supports data rates up to 112G PAM4; industry leading signal to noise performance
- Consistent signal integrity performance over the entire mating range
- Flexible architecture supports direct orthogonal, traditional backplane, mezzanine, coplanar and cable requirements up to 8P



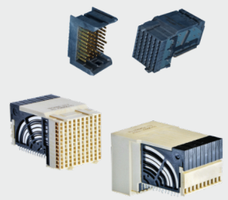
XCede®

- Supports designs from 8G to 56G PAM4
- Scalable and flexible design supports all your system requirements
- Supports Embedded Capacitors; mechanically robust



ExaMAX®

- Cost optimized with scalable performance to 112G PAM4
- Innovative design supports low insertion/extraction forces along with reduced crosstalk and low insertion loss
- Flexible architecture supports direct orthogonal, traditional backplane, coplanar and cable requirements
- Supports up to PCIe® Gen 7



AirMax®

- Cost optimized with scalable performance up to 56G PAM4
- Traditional backplane offering including standard and inverse gender
- Standard is 3-, 4- and 5-Pair

Cable Backplane Systems

www.amphenol-cs.com/cables/backplane.html

ExaMEZZ®

- Cost optimized with scalable performance up to 112G PAM4
- Innovative design supports low insertion/extraction forces along with reduced crosstalk and low insertion loss
- Stacked height range from 15 to 45.00mm in 2- and 4-Pair
  Configurations 14.5 to 67.00mm in 2- and 4-and 8-Pair configurations

HD Express®

- Supports PCIe® Gen5 through Gen 6
- Highest density PCIe® backplane family in the market
- Optimized for cost and scaleability
- Designed to support both high speed and low speed PCIe® signals

High Speed IO

amphenol-cs.com/connectors/high-speed-io.html

ExtremePort™ OSFP 224G Connectors

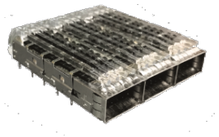
- Supports per port designs from 200G, 400G, 800G and 1.6T PAM4
- 8 lanes per cable – 28G, 56G, 112G and 224G per lane capability
- Thermal management engineered into cabled solution; available in all 4x form factors
- PAM4 modulation providing solutions up to 1.6T aggregate bandwidth

Mini-SAS HD External Connectors

- Capable of speeds up to 24Gb/s per channel (4 lanes, 8 lanes, 16 lanes available)
- Supports SAS 4.0 and PCIe® Gen 4.0 applications
- 32Gb/s for PCIe® Gen 5.0 solution in production.

200G QSFP DD Active Optical Cables (AOC)

- Capable of speeds up to 25.78125Gb/S or 28.056Gb/S per channel (8 lanes)
- Supports 200G Ethernet NRZ
- Maximization of linear port density



UltraPort®/ ExtremePort™ QSFP Connectors

- Supports per port designs from 100G, 200G and 400G PAM4
- Supports transmission speeds of up to 224G per lane
- Electrical interface employs 4 lanes that operate up to 56Gb/s PAM4 modulation
- Stacked, ganged and belly-to-belly connector and cage configurations

Mini-SAS HD Active Optical Cables (AOC)

- Capable of speeds up to 24Gb/s per channel (4 lanes)
- Supports SAS 2.1, 3.0, 4.0 and PCIe® Gen 3.0, 4.0
- Transmission distance up to 100m (MMF)

CDFP PCIe® Cable Assmeblies

- Supports designs from 28G, 56G PAM4, & 112G PAM4
- Passive cables in all 16x form factors; 28 AWG to 30 AWG

ExtremePort™ QSFP-DD 224G Connectors

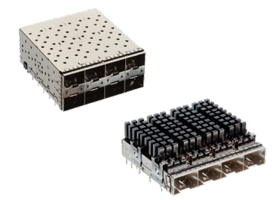
- Supports per port designs from 200G, 400G, 800G and 1.6T PAM4
- 8 lanes per cable – 28G, 56G, 112G and 224G per lane capability
- Double the bandwidth per port vs. QSFP
- Backwards plug compatibility with QSFP; available in all 4x form factors

100G QSFP Active Optical Cables (AOC)

- Capable of speeds up to 25.78125Gb/s or 28.056Gb/s per channel (4 lanes)
- Supports 100G Ethernet and Infiniband 4xEDR and 4x32 FC protocols
- Transmission distance up to 100m (MMF)

UltraPort®/ ExtremePort® QSFP Cable Assemblies

- Passive & active cables available in all 4x form factors: 26AWG to 32AWG cable
- Supports per port designs from 100G, 200G and 400G PAM4
- Supports transmission speeds of up to 224G per lane
- Great SI reliability and physical capabilities softer and better bending performance



UltraPort®/ ExtremePort™ SFP Connectors

- Supports designs from 28G, 56G PAM4 & 112G PAM4
- Backwards compatible with SFP28
- Electrical interface employs 1 lane that operates up to 112Gb/s PAM4 modulation
- Stacked, ganged and belly-to-belly board connector and cage configurations with heat sinks and light pipes

300G CXP2 Active Optical Cables (AOC)

- Capable of speeds up to 25.78125Gb/s per channel and 25Gb/s per channel (12 lanes)
- Can support Ethernet, CPRI or PCIe® Gen 4 protocols
- Up to 300Gb/s aggregate bandwidth

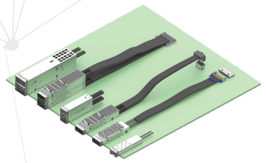
UltraPort®/ ExtremePort® SFP Cable Assemblies

- Passive & active cables available in all 4x form factors: 26AWG to 32AWG cable
- Supports designs from 28G, 56G PAM4 & 112G PAM4
- Fully compatible with Amphenol's SFP+/28/56/112 board connectors and cages as well as industry standard connector systems
- Supports cable length from 0.25 meter to 15 meter

OverPass™ Solutions

Portfolio of cable solutions to efficiently transfer high speed signals from the ASIC to anywhere within the system

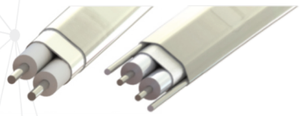
www.amphenol-cs.com/overpass



External High Speed IO

On package or near ASIC to external IO receptacles

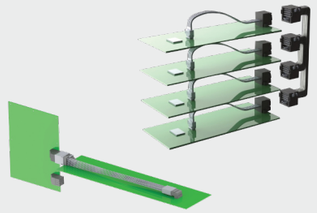
- Fully compliant to established industry standard interfaces: SFP, QSFP, QSFP DD, OSFP and others
- Supports transmission speeds of 28G, 56G and 112G per lane
- Press fit or cabled sideband signal management; engineered wire management
- Stacked, ganged, and belly-to-belly configurations coupled to high density (DP/mm2) near chip and on chip solutions



High Speed Bulk Cables

High frequency SkewClear EXD cable technology

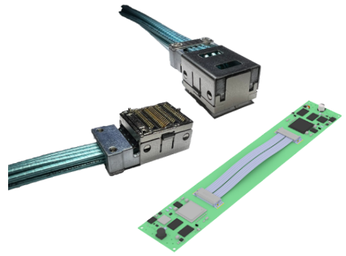
- Offerings include multi-pair cables: 2, 4 and 8 pair constructions in wire gages from 32AWG to 26AWG (34AWG in development)
- Supports transmission speeds of 10G, 28G, 56G, 112G, and 224G.
- Impedance tuned designs support: Paladin®, Paladin HD, ExaMAX®, ExaMAX+®, micro-LinkOVER™, Swift, Flash, Gen Z, OverPass™ HSIO, DenslLink™, UltraPass
- FEP insulated wiring for higher temperature environments



OverPass Cabled Backplane

Near ASIC to system backplane or coplanar cards

- Cable Backplane System portfolio products extend the reach of passive copper for next generation system designs
- Performance beyond 224G PAM4
- Optimization with our high speed, low loss twinax cable with PaladinHD2 and EXAMAX2 backplane connector families
- Flexible connector architecture supports cable blind mating with a backplane cable, press fit headers, right angle and orthogonalconfigurations
- Targeting support up thru future PCIe® 7.0 applications



UltraPass™ Internal High Speed IO

Near ASIC to card's or board's location in system

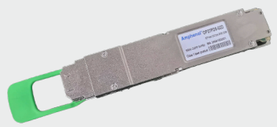
- Delivering a simple, low-loss, direct link to pluggable modules or anywhere in the system
- High speed, low profile and high density (bandwidth / mm2) near chip and on package solutions including micro-LinkOVER™ and DensiLink™
- Solutions available at 28G, 56G, 112G and 224G signaling speeds
- Multiple cable exit options including straight, right angle, and coplanar
- Construction options including double ended, Y, and breakout cables

Amphenol XGIGA

www.amphenol-cs.com/amphenol-transceivers

1.6T OSFP224 Transceivers

- OSFP224
- 2*DR4
- C-temp



1.6T OSFP224 TRO Transceivers

- OSFP224
- 2*FR4
- C-temp

1.6T OSFP224 LPO Transceivers

- OSFP224 LPO
- 2*DR4, AOC
- C-temp

800G OSFP112 DR4 RHS Transceivers (200G/lane optical)

- OSFP112 RHS
- DR4, FR4
- C-temp

800G OSFP Transceivers

- OSFP
- 2*SR4, 2*DR4, 2*FR4, 2*LR4, AOC
- C-temp

64G FC Transceivers

- SFP56
- SW,LW
- C-temp, E-temp

800G OSFP LPO Transceivers

- OSFP LPO
- 2*DR4, AOC
- C-temp

32G FC Transceivers

- SFP28
- SW,LW
- C-temp, E-temp

400G Transceivers

- QSFP-DD, QSFP112
- FR4, QSFP112 FR4, QSFP112 LPO
- C-temp

25G FC Transceivers

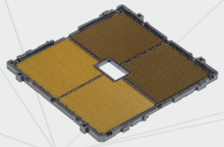
- SFP 28
- AOC, BIDI, SR, LR, ER, DWDM, BIDI LR, BIDI ER, CWDM
- C-temp, I-temp

100G Transceivers

- OSFP28, CFP, CFP2, CFP4
- SR4, LR4, ER4 LITE, ER4, ZR4, AOC
- C-temp

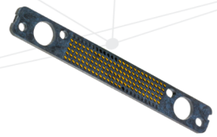
MeZZanine Products

www.amphenol-cs.com/mezzanine



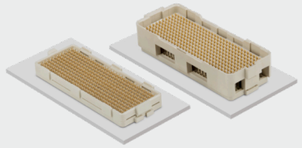
cLGA® High Speed Sockets

- Mechanically robust compression technology supporting designs with pin counts up to 10,000+ and 112Gb/s+ data rates
- High performance configurations available in both LGA/LGA and LGA/BGA form factors



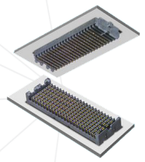
cStack™

- Configurable low profile compression solution available on .60mm to 1.27mm pitch in LGA/ LGA form factors
- Ideal for board to board and module to board applications



MEG-Array

- Provides the high density and high-speed benefits of a large array supported by the reliability and low costs of standard surface mount PCB assembly
- Features industry proven patented BGA interconnect design



Chameleon®

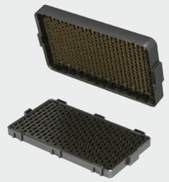
- Pin Field Flexibility: Offers differential pair, single ended and power configurations customized to match your design/ system requirements
- Allows maximum bandwidth while maintaining signal integrity

CAMM2 Connectors

- Compression Attached Memory Module connectors use Amphenol's cLGA® compression technology
- Designed for high reliability, and higher memory speeds, they also help improve thermals and save space

Lynx

- A 4-row product doubling the density in a 2-row footprint that is suitable for a wide variety of applications
- A flexible 0.60mm pitch solution designed for high speed and high-density differential or single-ended signaling board-to-board applications.



M-Series™

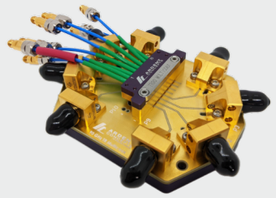
- Designed to support high technology products in board-to-board or flex assembly architectures from 4-15mm
- Next-generation differential pair contact design for 56G NRZ, 112G PAM4 performance

ARDENT CONCEPTS
An Amphenol Company

www.ardentconcepts.com

TR90™ Multicoax Connector

- Exceptional signal integrity out to 90 GHz
- Mates directly to PCB Footprint, no costly PCB solder-down leave behinds required
- Dense footprint (2.54mm signal-to-signal) gets TR closer to device under test
- Easy transition from existing TR40/70 GHz Multicoax implementations



TR90™ Multicoax Right Angle Connector

- Low profile form factor with exceptional signal integrity out to 90 GHz
- Available in 8 and 16 channel configurations
- Uses same footprint as TR90 Straight Mount
- Ideal for 112G/224G IC design characterization and validation

Substrate Launch Test Fixture (SLTF)

- Ideal for 112G/224G IC design characterization and validation
- TR Multicoax design is integrated with the Ardent SK high speed socket & lid for an all-in-one solution
- Compression interface requires no solder-down components on fragile substrates/silicon
- Minimize mounting and tooling points in PCB to make signal routing simpler for complex boards/devices
- Available in singled ended and differential configurations

TR Cryo™ Multicoax Connector

- Cryogenic-ready ganged coaxial cable assembly
- Ideal for quantum computing applications
- Multiple cable and connector configurations
- All metal, fully coaxial solderless compliant interface

Storage & Server IO

www.amphenol-cs.com/storage-server-io

EDSFF, OCP, Power Shelf and PCIe® DirectAttached Cable Connectors

- PCIe® DirectAttached® cable riser solution supports up to PCIe® Gen5
- EDSFF cable connectors for E1 / E3 specifications
- OCP cable connectors for OCP NIC 3.0
- Power Shelf cable connectors for ORv3

PCIe® M.2 & Ultra Slim M.2

- 67 contacts on 0.50mm pitch fully compliant with PCI-SIG PCIe® M.2 specification
- Meets PCIe® Gen 5 specs and targeted for PCIe® Gen 6
- Dual Stacked, Shielded versions are available
- Right angle, vertical and various connector heights and keying options offered

DDR5 SMT and SO-DIMM Memory module Connectors

- Vertical Surface Mount, 288Pin/ 287pin to support different CPU platforms. Support UDIMM, RDIMM and MRDIMM options.
- Right-Angled Surface Mount DDR5 SODIMM with full height offerings, reverse or standard key options.

GEN Z EDSFF Enterprise & Datacenter SSD Form Factor Working Group OPEN Compute Project

Mini and Hyper Cool Edge for EDSFF/ SFF-TA-1002 /SFF-TA-1037/ OCP/ GEN Z

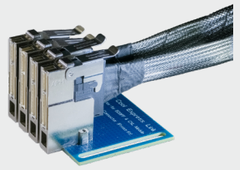
- 0.60mm pitch card edge connectors, meet PCIe® Gen 5/ Gen 6/112G PAM4 specs, targeted for PCIe® Gen 7
- Designed to meet SFF TA 1002, SFF TA 1037, EDSFF E1/E3, OCP NIC 3.0 and Gen Z specifications
- Vertical, right angle, straddle mount and orthogonal options are available

PCIe® CEM Connectors

- 1.00mm pitch card edge connectors, PCIe® Gen 4/5/6 and targeted for Gen 7
- X1, X4, X8, X16, X24, X32 standard links
- Extensive range includes vertical and straddle-mount with options for ridge/ridgeless, locked latch, side latch, blade hold down, open side wall, and more.

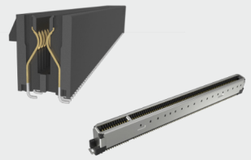
High mating cycle connectors for Test and Measurement Equipment

- Supports 100k cycle mating/ unmating – Ideal solution for test and measurement equipment
- Non-soldering type allows replacement of connector without damaging the main PCB after 100,000 cycles
- Supports DDR5 data rate



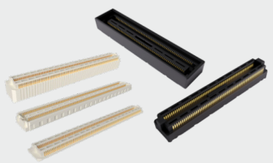
Cool Express Link™ EDSFF PCIe® Gen 5/6

- EDSFF E3 hybrid orthogonal PCIe® Gen 5/6 cable connector for next-gen storage applications
- Supports CXL 3.x memory low latency, high bandwidth, and high-speed data transmission for next-gen AI/HPC applications
- Hybrid connector design streamlines midplane design



PCIe® Flip CEM, Slim CEM, Metal Cage CEM

- Flip CEM with "JJ" or "LL" contacts provides better SI routing and smaller footprint
- Standard PCIe® CEM footprint is 8.20mm, Slim CEM is 6.00mm, Flip CEM is 5.90mm
- Metal cage CEM provides enhanced housing support



PCIe® Gen 6 COM-HPC & MiniStak

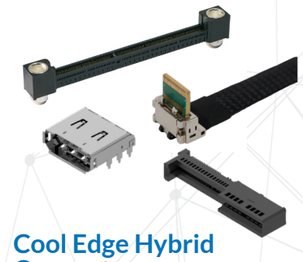
- Up to PCIe® Gen6 64Gbs per channel
- COM-HPC: 400pos 0.635mm supporting stack heights of 5mm and 10mm and provides CPU power support at 150W
- MiniStak: 0.60mm pitch 40pos to 400pos connectors withstanding 50G mechanical shock

U.2 SFF8639 Gen 5/6

- SFF 8639 connectors, ideal for NVME U.2 SSD, also compatible with SATA/SAS form factor SSDs and HDDs
- 2 SAS lanes supporting up to 24G data rate and 4 PCIe® lanes supporting up to 64G (PSAS 6.0) data rates

Memory LPCAMM Connectors

- Compress Mount Technology contacts provide lower height
- Provides faster transmission speed and higher bandwidth for memory
- Better airflow for improved thermal
- Flexibility of severability



Cool Edge Hybrid Connectors

- Slim Cool Edge: 0.65mm pitch, Gen 6 64G PAM4 connectors
- Standard Cool Edge: 0.8mm pitch connectors with EMI shielding for automotive and power applications
- Double Density Cool Edge: 0.8mm pitch connectors with highly configurable wafer design for differential, single-ended, and power applications
- One-piece small form factor

Power Solutions

www.amphenol-cs.com/power-solutions

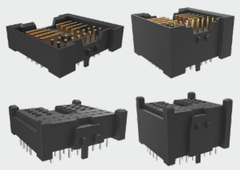
DATA CENTER

PwrBlade® ULTRA HD+ Board-to-Board

- Provides up to 100A per contact
- Low-profile configuration, 11.40mm height above board
- Highly configurable tooling design

PwrBlade® ULTRA HD+ Cable-to-Board

- Provides up to 100A per contact
- Squeeze-to-release latches
- Versatile wire ranges of 6 – 8AWG for power contacts



PwrBlade® MiniMezz

- Rated up to 50A per high power contact, 25A per low power contact
- Available in stack heights from 8.00mm to 20.00mm (tooled in 1.00mm increments)
- ± 0.80mm of gatherability for blind-mate applications

PwrBlade® Mini Cable-to-Board

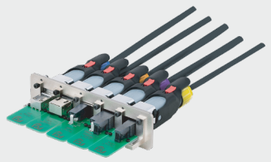
- Rated up to 25A per contact (50A per column)
- Built-in squeeze-to-release latches
- Latching CPA (connector position assurance) features

OCP M-CRPS HVDC 277VAC/380VDC

- Rated up to 30A per pin
- Touch-safe design
- Over-molded housing

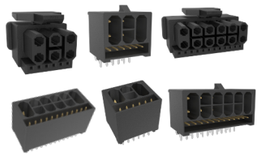
CoolPower® HD

- Wide power range of 100A – 250A per pin
- Pin diameters from 5.70mm – 9.10mm
- Flexible housing form-factor



OCTIS™ Outdoor I/O

- Robust I/O solution for high reliability and performance
- Multiple versions: Optical, RJ45, Power, Signal, Hybrid
- Field-terminable connector series



Minitek® Pwr PICPwr OCP Connector Solutions

- 12V connector solution support Open Compute Project Power Distribution and Management architecture requirements
- Operating power and voltage 864W at 12VDC

PwrBlade® Mini Board-to-Board

- Rated up to 45A per power contact
- Lowest-profile PwrBlade® connector (8.10mm height above board)
- No PCB overhang

OCP ORv3 BarKlip®

- Power ranging from 100 – 700A per contact
- Designed to meet OCP ORv3 Power Distribution standards
- Supports 48V Power Rack Architecture

BarKlip® BK220

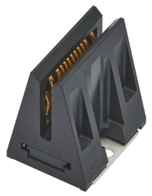
- Provides up to 220A per contact
- Ultra-low end-of-life resistance of 0.05mΩ
- Sense pin contacts for mate last-first break capability

BarKlip® BK150 & BK220 Nano I/O

- Power ranging from 150A – 220A per contact
- Fully Compliant with ORv3 IT Gear Connector Specification
- Sense pin contacts for mate last-first break capability

BarKlip® BK350 I/O

- Distributes up to 360A per contact
- Sense pin contacts mate last-first break capability
- Secondary chassis grounding contacts

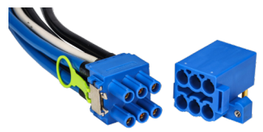


BarKlip® BK450

- Currents rated up to 450A per contact
- 36 independent points of contact for high current carrying capability
- ±3.50mm of gatherability for blind mate applications

ORv3 AC Input Connectors and Cable Assemblies

- 7-Pin connector designed for Star, Delta, and single-phase connections
- Fully compliant with OCP ORv3 Power Shelf Universal Input Connector Specification
- Rated up to 32A per pin



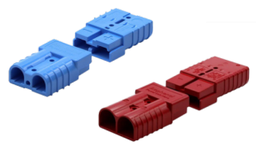
OCP M-CRPS +54V

- Rated up to 40A per pin
- Wiring options of 8, 10, & 12AWG
- Over-molded cable options available

ESS & E-Mobility

EnergyKlip™ EK Series

- Power ranging from 160A – 350A per contact
- IP67 rated seal to ensure protection
- Flexible cable or flex busbar options



IPC-M Connectors

- Wide power range from 50A – 350A per contact
- Wire-to-wire and Wire-to-board designs
- Touch-safe contacts

Minitek® Pwr Connector and Cable Assembly

- Wire-to-wire and wire-to-board solutions
- Current rating from 5A to 25A
- Available in pitch sizes of 3.00mm, 4.20mm, and 5.70mm

DuraEV™

- Provides continuous current of 70A and withstands 10,000 mating cycles
- IP67 rated portable and fixed battery connectors for charging and discharging electric vehicles
- Robust and durable solution

DuraSWAP™ Swappable Battery Connectors

- IP67 rated swappable battery connector
- Provides continuous current of 100A and withstands 10,000 mating cycles
- Connector mates in four different orientations

DuraSWAP™ Concentric

- IP67 rated to ensure protection
- Provides continuous current of 100A
- Rated for up to 10,000 mating cycles

Energy Pole

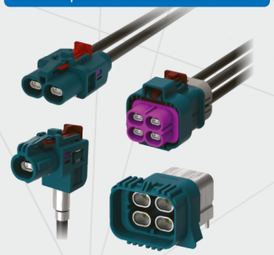
- Rated from 200A - 350A
- Automatic locking while mating
- 360° rotation for easy cable routing

Type-6 Charging Gun

- Fast and normal charging compatibility
- First mate-last break capability
- Drainage hole to prevent water retention

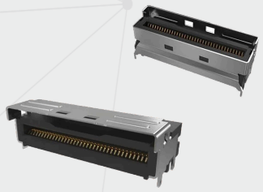
Commercial IO

www.amphenol-cs.com/commercial-io



Ve-NET™

- Developed according to USCAR-2 & LV214
- Using shielded twisted pair cables to support MULTI-GIG high data transmission rate
- Supports Automotive Ethernet, LVDS, APIX3, and FPD-Link IV

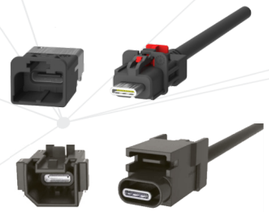


Mini Cool Edge IO

- Up to 64Gb/s PAM4, PCIe® Gen 4/5/6/7 over 1.0 meter transmission distance
- Cable/card insertion, dual applications are available
- Options for 92Ω, 85Ω and 95Ω impedance and various pin number options - meeting PCIe®/NVMe/SAS/SFP(+)/ QSFP specifications

Mid Power / TopFlight™

- Wire to Board solutions in 3.0mm and 4.2mm pitch
- Current rating from 6.5A to 20A per pin
- TopFlight™: Engineered for use in OCP power distribution and management architecture, current rating up to 14A per pin



Mini HSbridge+ / HSbridge+

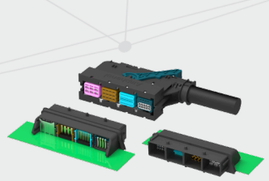
- Compliant with USCAR-30 USB and USCAR-2
- High data rate up to 10Gb/s, current rating up to 5A of power output
- Multiple volume and colour coding effectiveness complaint with automotive requirements

Multi-Trak™

- Combines original PCIe® and Mini Cool Edge IO in one connector to provide both power (21A) and high/low-speed signal
- Up to 56Gb/s PAM4, PCIe® Z 5, and target PCIe® Gen 6
- Options for 85Ω impedance and various pin number options - meeting PCIe®/NVMe/SAS/OCP DC-MHS/ SFF-TA-1033 specifications

RJMG & Discrete Magnetics

- 10/100T, 1GBT (10/100/1000-BT), 2.5G, 5G , 10G, Power Over Ethernet (PoE, 15W~150W) , integrated with surge protection.
- Commercial 0~70℃ and industrial -40~85℃ & -40~105℃ .
- Meets IEEE802.3ab and supports various Ethernet PHY



ComboNET™

- Features a scalable and compact size integrating Ve-NET, power pins, and various interfaces. Ideal for automotive zonal control units
- Each submodule is interchangeable, offering flexibility and convenience
- Compliant with USCAR-2 and LV214, and both sealed and unsealed versions are available

ExtremePort™ Z-link / ExtremePort™ Swift

- Z-Link Series: Compliant with Gen-Z and OCP NIC Specifications. SFF-TA-1002/1020
- Swift Series: Ultra-low profile, 0.60mm pitch connector with a mating height under 8.00mm. Supports speeds up to PCIe® Gen 5/Gen 6

SD/Micro SD Express Series Connectors

- PCIe® Gen3/4 x 1 lane, Gen4 x 2 lanes
- Push Push/ Push Pull types with card detect function
- Backward compatible with SD and micro SD card (UHS-I, UHS-II)

USB Type-C Connectors

- Performs to USB 4 and TBT5, and USB 3 compatible. Variety of center height options available. Module Type C supports TBT5 speed
- Waterproof range features unique O-ring technology (LIM), performs up to IPX8. 24-pin and 16-pin versions available.
- Power only range supports up to 240W (5A/ 48V) power supply

Fan Connectors

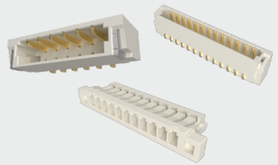
- Blind Mate Interface Wire to Board connectors from 1.25mm to 2.54mm pitch with max current rating 5.5A/pin. Designed for Server and Storage applications
- Card to Wire connectors in 2.44mm and 2.54mm pitch with current rating 4A/pin designed for switch application

DisplayPort 2.1 Connectors

- Support DP80(80/54Gbps)/ DP40(40Gbps)
- VESA certificate
- High performance signal integrity

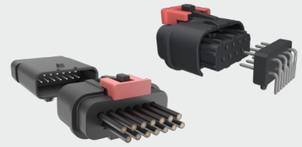
FCi Basics

www.amphenol-cs.com/basics



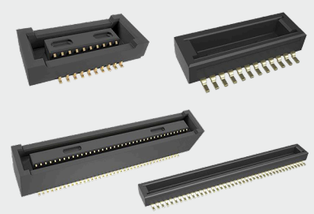
FitMate® 0.80mm

- 0.80mm pitch
- Fine pitch, low profile design
- Single row, 2 to 16 positions, 0.5A contact



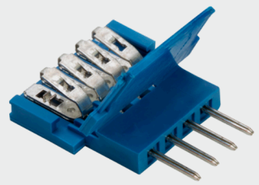
MicroSpace™ / MicroSpaceXS™

- 1.27mm pitch
- Crimp to Wire and Wire to Wire solutions
- LV214 S3, USCAR-T2V2 compatible



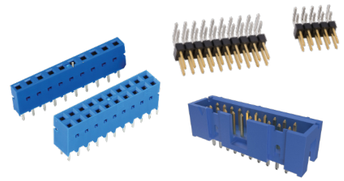
BergStak®

- 0.40mm pitch
- Wide range of stack heights and positions
- Speed up to 16Gb/s, USCAR-2 V2 qualified



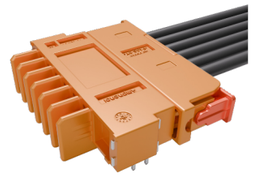
Clincher™

- 2.54mm pitch
- Industry standard for Membrane Switches
- 2 to 34 positions, 2A contact



Modular Systems

- 2.00 / 2.54mm pitch
- Wire to Board, Wire to Wire, Board to board, Flex to Board solutions
- Single, double row, wide range of positions



HVLock®

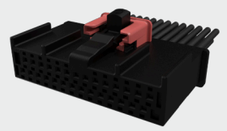
- 4.50mm pitch
- Single Row, 6 to 10 positions
- USCAR-2, LV-214 S2 compatible

DensiStak™

- 0.80mm x 1.25mm pitch
- High Density up to 1034 pos
- Speed up to 16Gb/s, USCAR-2 compliant

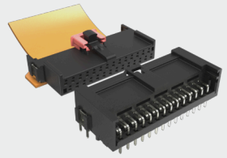
USB Type C

- Wide range including Waterproof
- Connectors and cable assemblies
- Speed up to 40Gb/s, up to 10,000 cycles



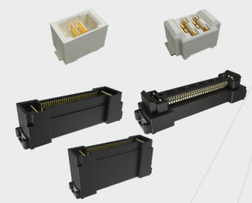
WireLock®

- 1.80mm pitch
- Highly vibration resistant, low mating force
- USCAR-2 V2 and LV-214 S2 compliant, 2A contact



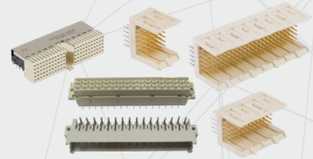
FlexLock™

- 2.54 / 3.20mm pitch
- Easier assembly, less weight, lower cost
- USCAR-T2V2, LV-214 S3 compatible



ComboStak® PowerStak®

- 0.50 / 2.00mm pitch
- Hybrid and Medium Power solution
- Speed up to 20Gb/s, 0.5A signal 25A power



Industrial Backplane Connectors

- 2.00mm Millipacs® Hard Metric connector; 2.00mm Metral® Future Bus connector & 2.54mm DIN 41612 connector for robust industrial applications
- Features dual beam signal contacts for high reliable electrical performance

Amphenol AORORA

www.amphenol-cs.com/aorora

Commercial Industrial

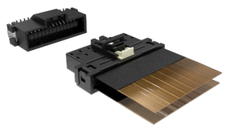
www.amphenol-cs.com/commercial-industrial

FloatCombo™ Floating Board-to-Board Connector System with Power Pin

- 0.50mm pitch connector with 4 independent power pins
- Supports 5A current per power pin and high-speed data rates up to 16Gb/s
- Various stacking heights from 8.00mm to 30.00mm with large floating allowance
- USCAR-2 T3V2 qualified

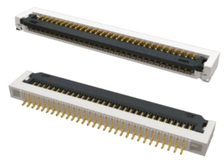
Single Pair Ethernet Connectors & Cables

- Next gen ruggedized interface
- IEC 63171-6, PoDL
- IP20 & IP67 connectors & cables
- Industrial Ethernet to the sensor and actuator level
- Multidrop Solutions



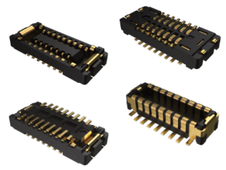
FlexFast™ Flex-to-Board Connector Solution

- Compact size and low-profile flex-to-board connection solution
- Available in pitch sizes of 0.65mm, 1.00mm, 1.80mm, 2.00mm, and 3.00mm, with pin counts ranging from 12 to 80 pins, offering a complete product family for customer selection
- Automotive-grade compliant with USCAR-2 and LV 214 specs
- Designed for Battery Management Systems (BMS), battery packs, and inverter+DC-DC converter applications
- Capable of handling high-current applications while remaining lightweight for automotive use



FFC/FPC Connectors

- From 0.21mm to 2.00mm pitch with various heights ranging from 0.50mm to 6.25mm
- Easy to operate and high vibration-proof performance
- Automotive grade versions compliant with USCAR-2 and LV 214 are available
- FFC cable can be supported as a whole solution
- Autolock option available



Micro Board-to-Board

- Low profile and fine pitch for high density applications
- High current rating (Up to 5A)
- Chamfer connector design prevents mismatching

Lighting Connectors & Cables

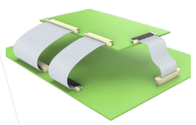
- Lighting connectors & cables
- NEMA/ANSI C136.41
- Zhaga Book 18 and Book 20
- LED indoor, outdoor, street lighting applications

ix Industrial™ Ethernet Connectors & Cables

- Next gen ruggedized interface
- IEC 61076-3-124, Cat6A, PoE++
- IP20 & IP67 connectors & cables
- ix-Mag with integrated magnetics
- Factories, Robotics applications

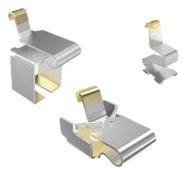
D-Sub Connectors & Cables

- SMT Standard Connectors
- Slimline SMT Connectors
- High Current Connectors & Cables
- Accessories (Hoods, Backshells)
- Customized Connectors & Cables



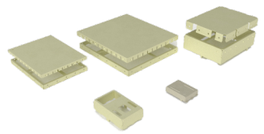
FFC Jumper

- Easy to operate
- Available in numerous circuit sizes (4 to 60)
- Both Type S (same-side) and Type O (opposite-side) available
- PET Insulation



Spring Contacts

- Wide variety of heights ranging from 1.00mm to 20.00mm are offered as standard products
- Space saving design, suitable for compact devices
- Formed by one-step stamping, easy to be assembled



EMC Shields

- Wide variety of profiles and sizes to accommodate mother/ daughter board configurations
- Option available for Two-Piece solution allowing convenient access to components
- Ideal for automated pick-and-place applications

Ruggedized

- Ruggedized, IP67 sealed
- Connectors & cables
- RJ, USB, USB-C, D-Sub, HDMI
- MRD circular latching
- FLH rectangular latching
- Industrial, commercial, lighting

RJ / Modular Jacks & Modular Cable Assemblies

- Cat5, Cat5e, Cat6, Cat6A
- Single port, ganged, stacked multi-port, LEDs, shielded
- Vertical, right angle
- PoE++ capability
- Industrial, commercial, medical, consumer, military applications
- Cable Assemblies

Industrial RJ Plugs

- Ruggedized RJ plugs & cables
- IDC termination, field installable
- Metal latching, full metal construction
- Cat6A, fully shielded
- Multiple cable entry angle options
- Factory and other applications

Amphenol

COMMUNICATIONS SOLUTIONS

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